



**DEFENSE LOGISTICS AGENCY**  
DEFENSE SUPPLY CENTER, COLUMBUS  
POST OFFICE BOX 3990  
COLUMBUS, OH 43216-5000

IN REPLY  
REFER TO

DSCC-VQ (VQC-06-011644/Mr. Grammens/614-692-0604/dg)

SUBJECT: Certification for Assembly and Test Services, MIL-PRF-38535, FSC 5962

Mr. Robert C. Corrao  
President  
Corwil Technology Corporation  
1635 McCarthy Blvd.  
Milpitas, CA 95035

Dear Mr. Corrao:

Corwil has demonstrated to the Defense Supply Center, Columbus (DSCC) that it complies with MIL-PRF-38535, the performance specification used by the Department of Defense for monolithic integrated circuits.

Corwil is granted full Q level certification, effective August 30, 2006, this supersedes the previous transitional Q level certification letter DSCC-VQ-02-002452 for the technology flows used for the quality assurance levels listed in the enclosure.

Testing must be performed using the facilities and methods listed in the Laboratory Suitability letter DSCC-VQC-06-011643, or at facilities approved by the Corwil Technical Manufacturing Technical Review Board using its MIL-PRF-38535 Quality Management Program Plan Document # QAS-0100 Rev-15.

This certification is subject to the conditions in DoD 4120.24-M, Defense Standardization Program.

Any and all of the facilities mentioned on the enclosure are subject to an audit by the Qualifying Activity at any time. The manufacturer shall be responsible for all audit expenses incurred for the offshore facilities. Offshore facilities are subject to all of the conditions of MIL-PRF-38535, Appendix E.

QPL/QML manufacturers shall notify the qualifying activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem on their QPL/QML products. Failure to provide prior notification may be grounds for removal from QML-38535.



In addition, it is requested that the following activities be reported promptly to DSCC:

- Changes to certified facilities, process flows, or approved testing subcontractors
- Problem evaluation and a corrective action when:
  - a. A Technology Conformance Inspection (TCI) failure has been validated
  - b. The reliability of shipped parts is questionable.
- Test optimization, including:
  - a. Implementation - paragraph J.3.12, Appendix J, MIL-PRF-38535
  - b. Changing, suspending or canceling a prior test optimization
- Additions or deletions of parts in the QML-38535
- Change of company QML contact or other key QML personnel

This certification is valid until terminated by written notice from the Qualifying Activity. If warranted, it may be withdrawn by this Center at any time.

If you have any questions please contact Mr. Michael Grammens at (614) 692-0604.

Sincerely,

ROBERT P. EVANS  
Chief  
Sourcing and Qualification Unit

Enclosure

cc:  
Corwil (Dick Nelson)  
VQC (Scott Thomas)  
VQC (Michael Grammens)

**Visit us on the web at: [www.dsccl.dla.mil/offices/VQ](http://www.dsccl.dla.mil/offices/VQ)**

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<u>OPERATION</u>	<u>FACILITY</u>	<u>LOCATION</u>	<u>TECHNOLOGY</u>
<b>Design:</b>	N/A	N/A	N/A
<b>Wafer:</b>	N/A	N/A	N/A
<b>Fabrication:</b>	N/A	N/A	N/A
<b>Assembly:</b>	Corwil	1635 McCarthy Blvd. Milpitas, CA 95035	Wafer Dicing & die Inspection.  Package Assembly: Side Braze, Cerdip, Cerpack, Cerquad, PGA, Flatpack, LCC, J-lead CC, and Ceramic SOIC
<b>Test:</b>	Corwil	1635 McCarthy Blvd. Milpitas, CA 95035	Screening as baseline by Lab Suitability information letter DSCC-VQC-006-011643